

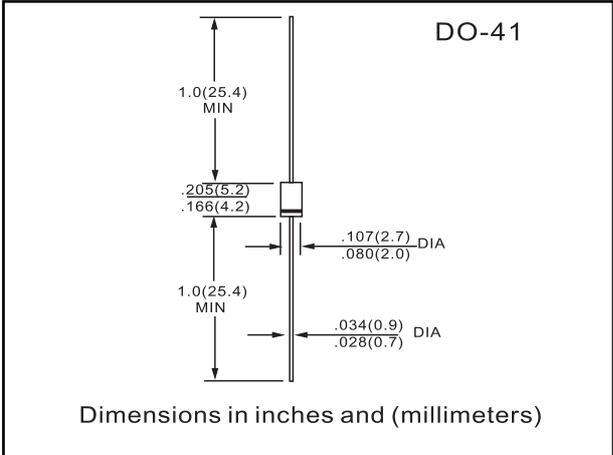


**TAYCHIPST**

SCHOTTKY RECTIFIER

**11DQ05 THRU 11DQ06**  
50V , 60V 1.1A

- FEATURES**
- Low profile, axial leaded outline
  - High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
  - Very low forward voltage drop
  - High frequency operation
  - Guard ring for enhanced ruggedness and long term reliability



**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

**Maximum Ratings:**

Characteristics	Symbol	Condition	Max	Units
Peak Inverse Voltage	$V_{RWM}$	-	50	V
			(11DQ05)	
Max. Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_L = 84^\circ C$ , rectangular wave form	1.1	A
			(11DQ06)	
Max. Peak One Cycle Non-Repetitive Surge Current	$I_{FSM}$	8.3 ms, half Sine pulse	30	A

**Electrical Characteristics:**

Characteristics	Symbol	Condition	Max	Units
Max. Forward Voltage Drop *	$V_{F1}$	@1 A, Pulse, $T_J = 25^\circ C$	0.58	V
		@2 A, Pulse, $T_J = 25^\circ C$	0.76	
Max. Reverse Current *	$I_{R1}$	@1 A, Pulse, $T_J = 125^\circ C$	0.53	mA
		@2 A, Pulse, $T_J = 125^\circ C$	0.64	
Max. Junction Capacitance	$T$	@ $V_R = \text{Rated } V_R$ , Pulse, $T_J = 25^\circ C$	1.0	pF
		@ $V_R = \text{Rated } V_R$ , Pulse, $T_J = 125^\circ C$	11	
Typical Series Inductance	$L_S$	@ $V_R = 5V$ , $T_C = 25^\circ C$ $f_{SIG} = 1MHz$ Measured lead to lead 5 mm from package body	55	nH
Max. Voltage Rate of Change (Rated $V_R$ )	dv/dt		8.0	$V/\mu s$
			10,000	

**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Max	Units
Max. Junction Temperature	$T_J$	-	-40 to +150	$^\circ C$
Max. Storage Temperature	$T_{stg}$	-	-40 to +150	$^\circ C$
Maximum Thermal Resistance Junction to Ambient	$R_{\theta JA}$	DC operation	100	$^\circ C/W$
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	DC operation	81	$^\circ C/W$
Approximate Weight	wt	-	0.33	g
Case Style	DO-41(DO-204AL)			

**RATINGS AND CHARACTERISTIC CURVES 11DQ05 THRU 11DQ06**

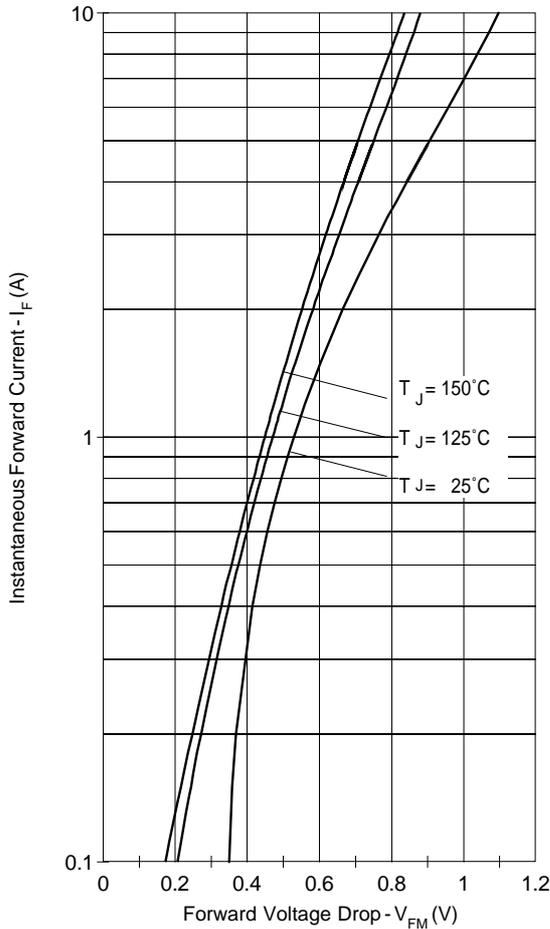


Fig. 1 - Maximum Forward Voltage Drop Characteristics

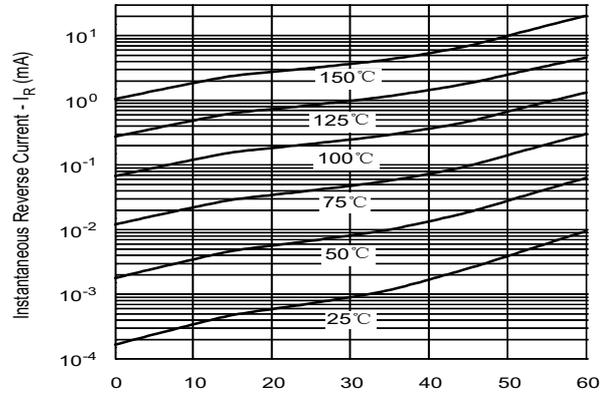


Fig. 2 - Typical Values of Reverse Current Vs. Reverse Voltage

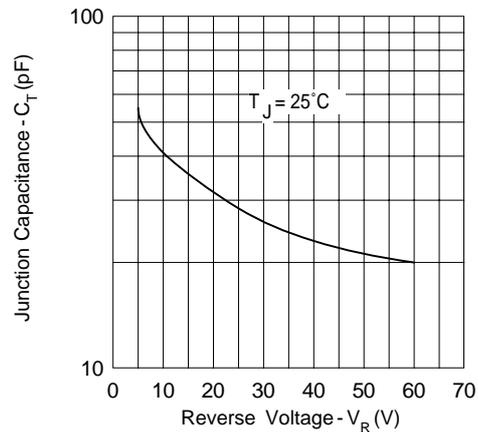


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage

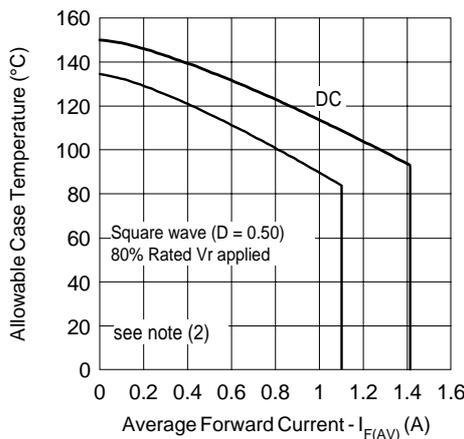


Fig. 4 - Maximum Ambient Temperature Vs. Average Forward Current, Printed Circuit Board Mounted

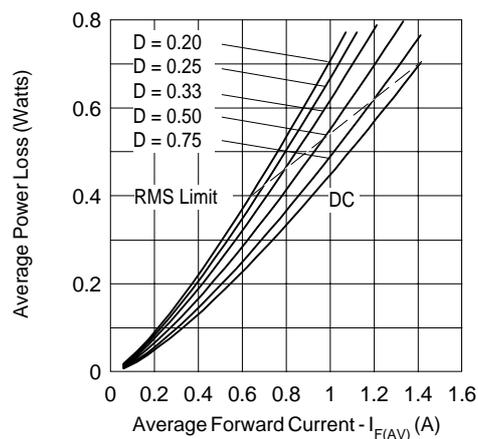


Fig. 5 - Forward Power Loss Characteristics

(2) Formula used:  $T_c = T_j - (Pd + Pd_{REV}) \times R_{thJC}$ ;  
 $Pd = \text{Forward Power Loss} = I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$  (see Fig. 6);  
 $Pd_{REV} = \text{Inverse Power Loss} = V_{R1} \times I_R (1 - D); I_R @ V_{R1} = 80\% \text{ rated } V_R$